
The 3D IC, WLP & TSV Packaging Newsletter

MEDIA KIT

Document valid till the end of 2008

WHAT YOLE DÉVELOPPEMENT IS DOING to help you reach your decision makers

With 10,000 qualified readers involved in 3D IC and TSV packaging, Yole Développement offers you a number of advertisements to reach targeted audiences in the field of Packaging



The mission of 3D IC & TSV Packaging Newsletter and I-Micronews website is to:

- Present a detailed analysis on Packaging technologies and related players.
- Provide you the feedback of companies deeply involved in the development of Packaging solutions.
- Select news that will impact the Packaging industry, according to Yole's experts.
- List key 2008 Packaging events all around the world.
- Present Yole's latest marketing analysis on Packaging industry.



Two Complementary Media

DEDICATED TO THE PACKAGING INDUSTRY

Yole Développement monitors for several years advanced packaging technologies and related applications. Because of its technological and marketing knowledge, the consulting company created a magazine and a website dedicated to 3D IC, WLP & TSV industry in 2006.

→ **3D IC, WLP & TSV Packaging Newsletter is a unique magazine for a growing business (without subscription)**

- Between 16 and 20 pages
- Bi-monthly newsletter
- Diffusion by email blast & printed copies at key advanced packaging events
- Contents: marketing & technological analysis, interviews, news...



→ **I-Micronews advanced packaging sections**

- Updated daily with reports, interviews, news...
- About 4000 readers per week for a total of 6000 unique visitors per month



www.i-micronews.com

THE 3D IC, WLP & TSV PACKAGING NEWSLETTER

Created in 2007, the 3D IC, WLP & TSV Packaging Newsletter, counts today almost 10,000 readers:

→ From managers to researchers, including marketing or business development managers, our readers represent the largest part of the 3D IC, WLP & TSV Packaging players.

→ The 3D IC, WLP & TSV Packaging Newsletter, is based on the expertise and network developed by Yole Développement, with its reports, analysis, interviews and latest key industry news on 3D IC, WLP & TSV Packaging, the newsletter is unique in the Semiconductor industry.

→ The objectives of our editors are to analyze the latest marketing and technological trends. In each issue, Yole Développement presents the state of art of the market and its related technologies: the reports are a feedback of 3D IC, WLP & TSV experts.

The 3D IC, WLP & TSV Packaging Newsletter is a bi-monthly newsletter. Its diffusion is based on email blasts and printed copies at the key 3D IC, WLP & Packaging conferences.

I-Micronews / 3DIC NewsletterTeam

Managing Director

Jean Christophe Eloy

eloy@yole.fr

Chief Editor

Eric Mounier

mounier@yole.fr

Editor of 3DIC newsletter

Jerome Baron

baron@yole.fr

Marketing

David Jourdan

jourdan@yole.fr

Business Development/ Advertising

Sandrine Leroy

leroy@yole.fr

Publisher

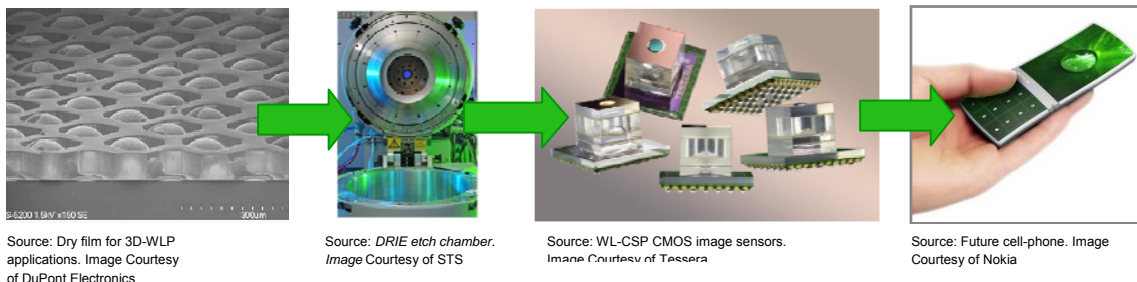
Benoit Deniau

deniau@yole.fr

AUDIENCE PROFILE

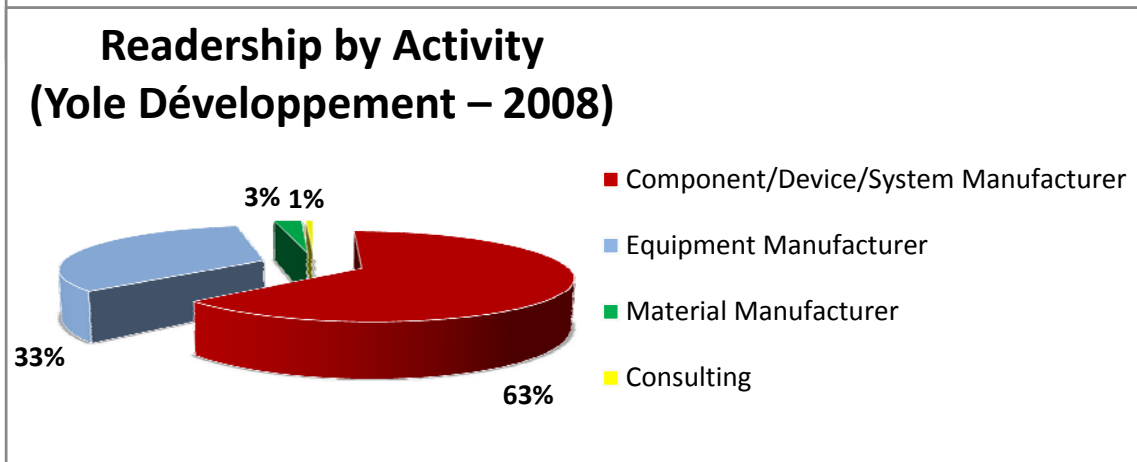
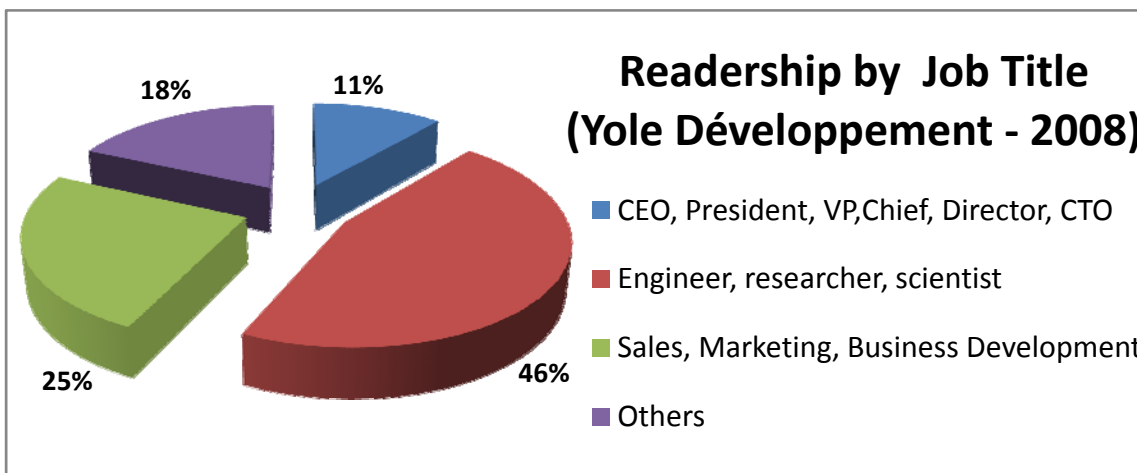
3D IC, WLP & TSV Newsletter's readers belong to all part of the Packaging supply chain:

From Materials – to Equipment – to Devices – to System.



Who are our readers?

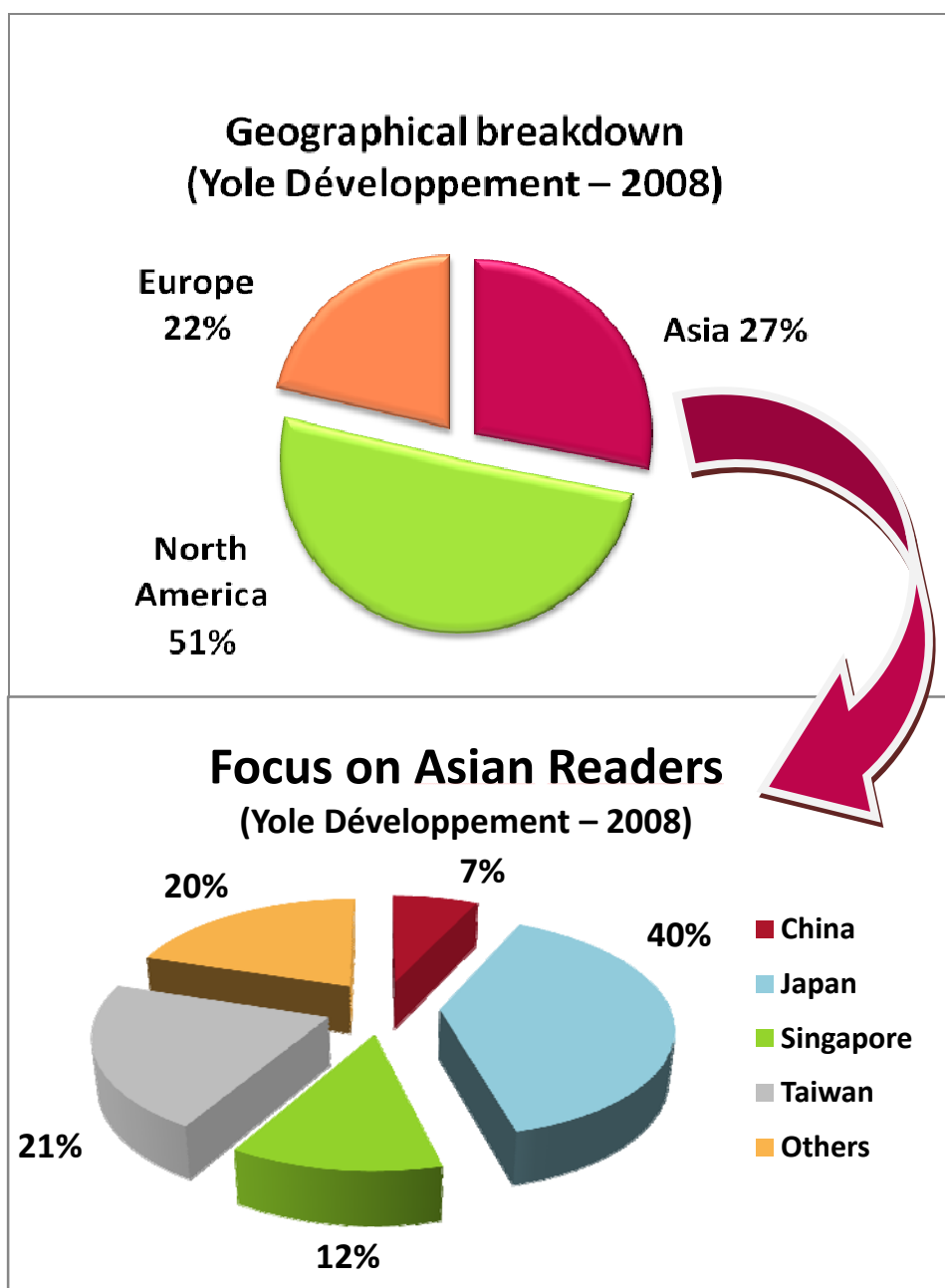
- 63% of our readers are involved in Devices & System industry.
- Almost 50% are coming from R&D and Engineering department.



3D IC, WLP & TSV Newsletter’s readers come from to the worldwide Packaging Industry.

Where are our readers?

→ Asian readers represent 28% of the 3D IC, WLP & TSV Newsletter readership.



THE 3D IC, WLP & TSV NEWSLETTER

- “Confidential Newsletter” in collaboration with key players of Advanced Packaging industry
- Circulation by email blast: 10,000 qualified readers
- Printed version distributed at key 2008 events of the Advanced Packaging industry: *Pan Pacific Symposium, Int. Conf. & Exhibition on Device Packaging 2008, ECTC, Semicon West, Semicon Europa, International Wafer Level Packaging Conf. ...*

HIGHLIGHTS – EDITORIAL CALENDAR 2008

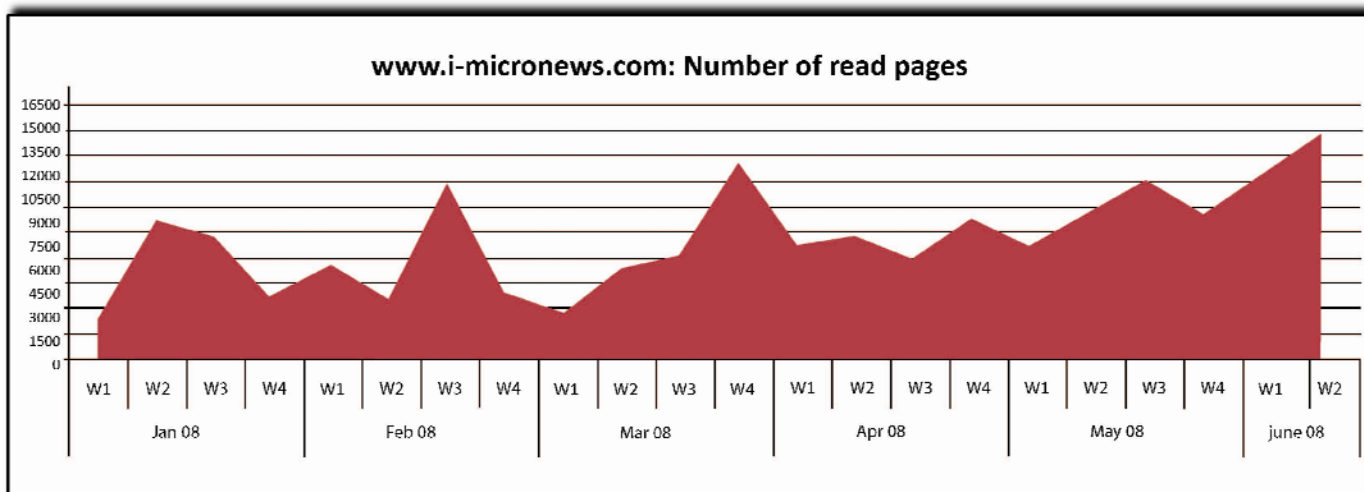
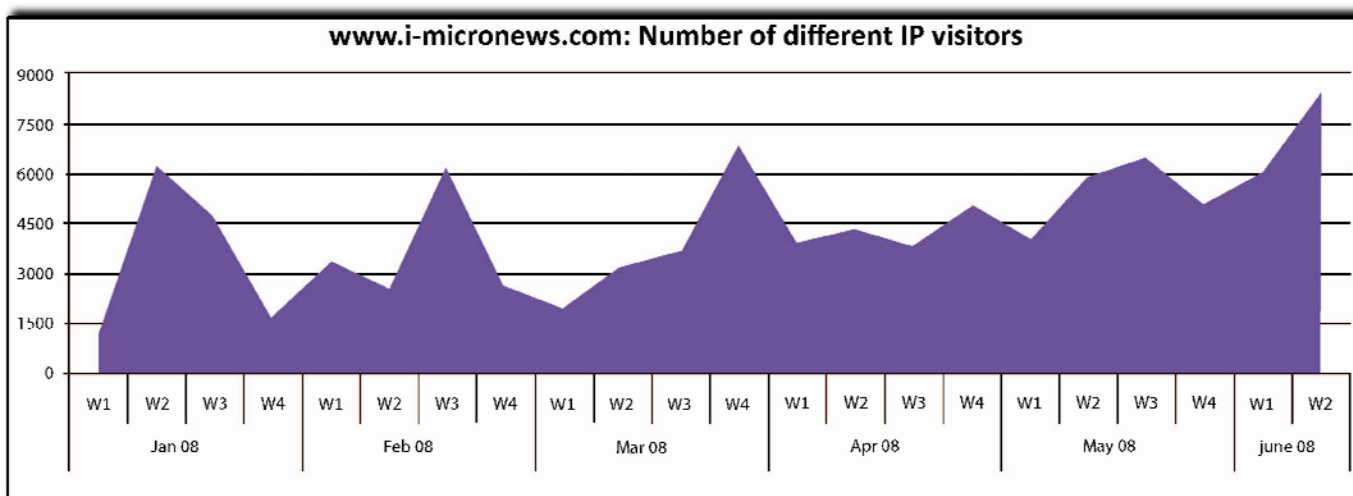
Issues	Advanced Packaging
10/07 – #1	-
12/07 – #2	Semicon Japan 2007
01/08 – #3	Pan Pacific Symposium 2008
03/08 – #4	Int. Conf. & Exhibition Device Packaging 2008 - IMAPS
05/08 – #5	ECTC 2008
07/08 – #6	Semicon West 2008
09/08 – #7	Semicon Europa 2008 International Wafer Level Packaging Conf. (SMTA)
11/08 – #8	3-D Architectures for Semiconductor, Integration & Packaging (RTI Tech Venture), Semicon Japan 2008

I-MICRONEWS WEBSITE

→ Dedicated to 3D IC, WLP & TSV web pages

→ Updated daily

→ 4000 readers per week for a total of 6000 unique visitors per month



ANNUAL SPONSORSHIP

Yole Développement offers you a portfolio composed of the 3D IC, WLP & TSV newsletter and the website I-Micronews (Advanced packaging web pages):

→ GOLD sponsorship:

- The magazine:
 - One full page per issue, during one year – 6 issues
 - Recognition as Media Sponsor with Company Logo – 6 issues
- Email blast: One sponsorship (including logo and company's description - 150 words)
- I-Micronews: a dedicated banner during 3 months

Rates: € 6 900

→ SILVER sponsorship

- The magazine:
 - One full page per issue, during one year – 6 issues
 - Recognition as Media Sponsor with Company Logo – 6 issues
- Email blast: One sponsorship (including logo and company's description - 150 words)
- I-Micronews: a dedicated banner during 3 months

Rates: € 4 900

ADVERTISEMENT IN ONE SPECIFIC ISSUE OR BANNER ON I-MICRONEWS

We offer you the opportunity to select one issue according to your communication calendar. You can insert full page, half page ... (see our rates next page)

Moreover, we propose you to be a partner of the website with a banner on I-Micronews (www.i-micronews.com).

- **Contact:** Sandrine Leroy (leroy@yole.fr),
Tel: (+33) 472-830-189 Fax: (+33) 472-830-180

RATES

- The 3D IC, WLP & TSV Packaging Newsletter

Newsletter	Size Width x Height	Advertising Rates		
		1x	2x	3x
Full page spread	-	€ 3000	€ 2000	-
Full page	H 10.75 inch x W 7.33 inch	€ 2000	€ 1600	€ 1500
Half page (horizontal or vertical)	H 3.58 inch x W 10.75 inch	€ 1600	€ 1500	€ 1400

- The website I-Micronews

I-Micronews	Dimensions	Rates (CPM) *	
		Random Rotation*	Specific Thematic*
Full page intro	940 x 600	-	€ 450
Vertical Banner	728 x 90	€ 300	€ 350
Square Banner	270 x 240	€ 200	€ 250
Horizontal	160 x 600	€ 320	€ 350

* CPM: Cost Per Thousand pages viewed with advertising.

- Other advertising possibilities

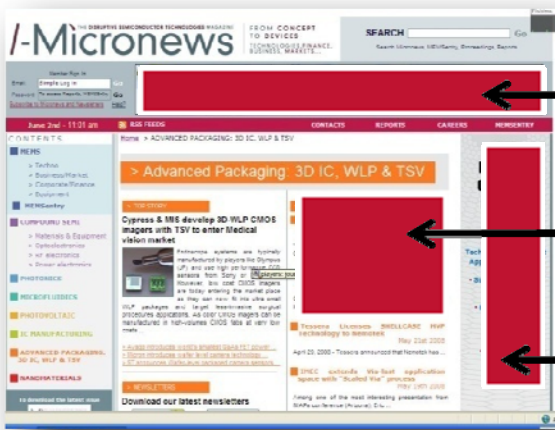
- ⇒ Logo on the cover of the magazine: € 500 per issue
- ⇒ Presentation of the company in email blast: 1X: € 2500/ 2X: € 2000
(Including logo and company’s description: 150 words)

SPECIFICATIONS

→ I-Micronews, the website:

Format: JPEG, Flash, GIF

Full page intro
940 x 600 pixels
(80k file limit)



Horizontal banner
160 x 600 pixels
(35k file limit)

Square banner
270 x 240 pixels
(35k file limit)

Vertical banner
728 x 90 pixels
(35k file limit)

→ The magazine:

Format: PDF



Full page spread
186 mm x 273 mm per page
7.33 inch x 10.75 inch per page



Half page - Vertical
90.5 mm x 273 mm
3.56 inch x 10.75 inch



Full page
186 mm x 273 mm
7.33 inch x 10.75 inch



Half page – Horizontal
186 mm x 132 mm
7.33 inch x 5.20 inch

SPECIFIC TERMS & CONDITIONS OF SALES FOR YOLE'S PUBLICATIONS

1. All orders are subject to acceptance by YOLE DÉVELOPPEMENT.
2. No conditions other than those set forth in this rate card shall be binding upon Yole Développement unless specifically agreed to by YOLE DÉVELOPPEMENT in writing.
3. Positioning of advertisements is at the sole discretion of YOLE DÉVELOPPEMENT except where a specific position has been agreed to by YOLE DÉVELOPPEMENT in writing.
4. Cancellations or changes in advertising by the advertiser or its agency may not be made after the closing date for the publication or product, unless otherwise agreed upon between the parties in writing. YOLE DÉVELOPPEMENT is under no obligation to revise advertising materials not received by the YOLE DÉVELOPPEMENT production department by the closing date and such advertisements may not be subject to approval by the advertiser or its agency.
5. YOLE DÉVELOPPEMENT assumes no liability for any errors or omissions in key numbers appearing in advertisements provided by the customer.
6. YOLE DÉVELOPPEMENT is not liable for any delays in the production or delivery of the publication or product due to any conditions beyond Yole's control.
7. In consideration of Yole's publishing advertising (or distributing another product) for the advertiser, the advertiser and its agency, agree to indemnify and defend YOLE DÉVELOPPEMENT against any and all claims, losses, liabilities, damages and expenses (including attorneys' fees) arising out of Yole's printing, publishing or distributing such advertising (or another product) and/or arising from third parties' access to advertiser's site and use of advertiser's products or services.
8. In no event shall YOLE DÉVELOPPEMENT be liable for any consequential, incidental or special damages nor shall its liability for any act, error or omission, whether or not due to its negligence, exceed the price paid to YOLE DÉVELOPPEMENT for the publication or distribution of such materials.
9. YOLE DÉVELOPPEMENT reserves the right to hold the advertiser and its agency jointly and severably liable for all monies that are due and payable to Yole Développement.
10. Advertising in Yole's online products and services is subject to the terms of the applicable online insertion order.
11. All payments are due within thirty (30) days of the invoice date. Non commissionable charges, such as production charges, are not subject to an advertising agency commission. Agency commissions are not payable on invoices which are not paid within (90) days of the date of the invoice. Advertiser shall pay a late charge of 1% per month (12% per year) on all invoices not paid within (30) days of the date of such invoices.